BOSCH MEMS SENSORS: ENABLER FOR THE IOT

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OUTLINE

- 1 INTRODUCTION | MEMS OVERVIEW & MEMS@BOSCH
- **Q AUTOMOTIVE MEMS** | TECHNOLOGY & APPLICATIONS
- ()3 CE MEMS | DRIVING TECHNOLOGY INNOVATION
- **MEMS FOR IOT | ENABLING NEW APPLICATIONS**





01 INTRODUCTION

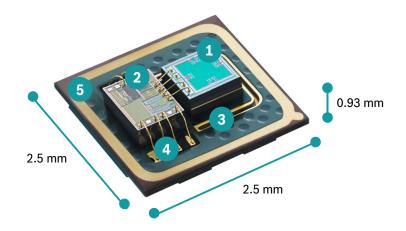
MEMS OVERVIEW & MEMS @ BOSCH



What are MEMS?

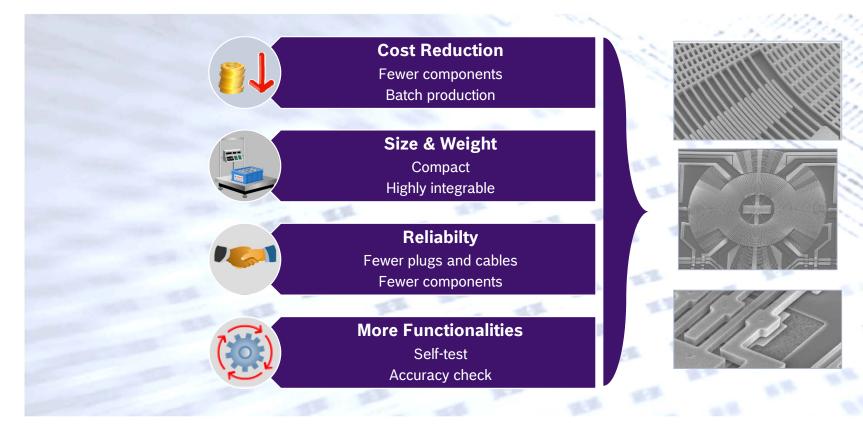
Micro-Electro-Mechanical Systems

- ► MEMS are miniature systems that combine tiny mechanical structures with electronic circuits. Typical individual structures have a size of a few μm.
- ▶ The MEMS sensor element is usually packaged together with an ASIC and made into one unit, e.g. into a LGA package.



- 1 MEMS
- 2 ASIC
- 3 Decoupling unit
- 4 Bonding wires
- 5 Printed circuit board (PCB)

Technology Why MEMS technology?

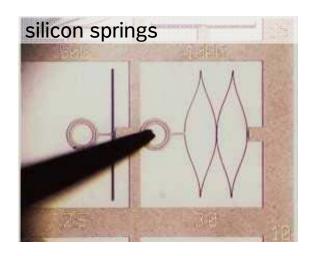




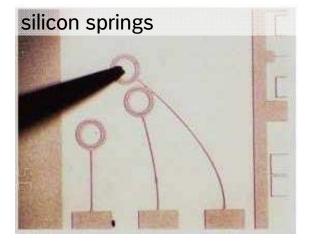
Technology Mechanical properties of silicon

Silicon compared to steel

- ► Over 3 times lower density
- ▶ 4 times higher yielding strength
- ▶ 3 times lower thermal expansion
- ► Brittle material, no plastic deformation









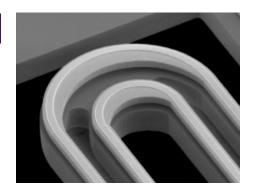
Technology MEMS technology

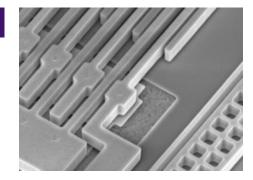
Bulk Micromachining

- ► Structure definition by selective etching
- ▶of bulk wafer
- Structures are monocrystalline
- ► Contamination risks (potassium, natrium, ...)

Surface Micromachining

- ▶ Structures are made on top of wafer by deposition
- ▶and selective etching
- ▶ Structures are of poly silicon and silicon dioxide
- ▶ Few contamination risks

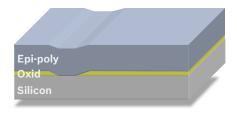


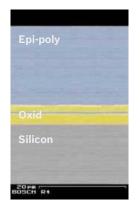




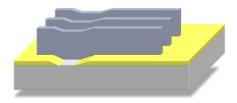
Automotive sensors – Angular rate sensors MEMS technology: surface micromachining

Thick epitaxy ("epi-poly")



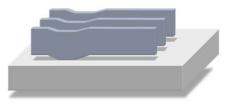


DRIE ("Bosch-process")





Sacrificial etching of oxide

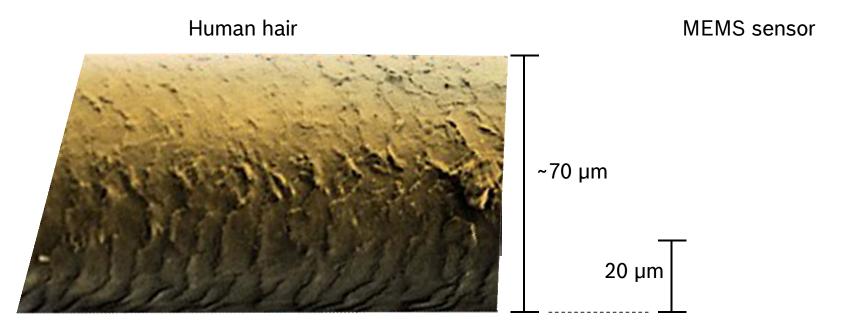






Technology MEMS technology: surface micromachining

...comparison to a human hair

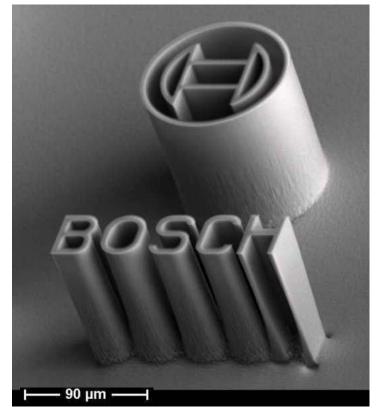




Technology DRIE – the Bosch process

- ► Deep RIE of silicon trenches
- ► Alternating etch- (SF6) and passivation cycles (C4F8)
- ► High aspect ratio (>>10:1)
- ► High anisotropy (underetch <<2 % of etch depth)
- ► High etch rate

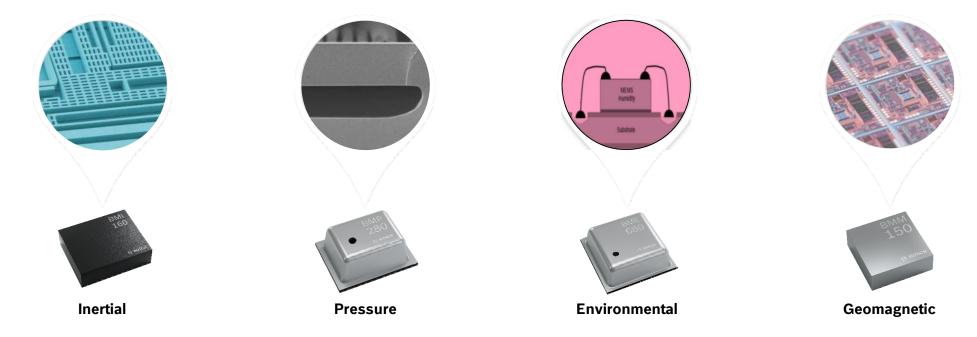






MEMS challenge:

One product / one technology



Each product segment requires specific technology (not fully CMOS compatible) Challenge for integration, need for advanced packaging technologies (SiP)



Waves of MEMS sensor proliferation



2nd wave

Consumer Electronics

3rd wave

Internet of Things (IoT)



1st wave

Automotive

1990

2000

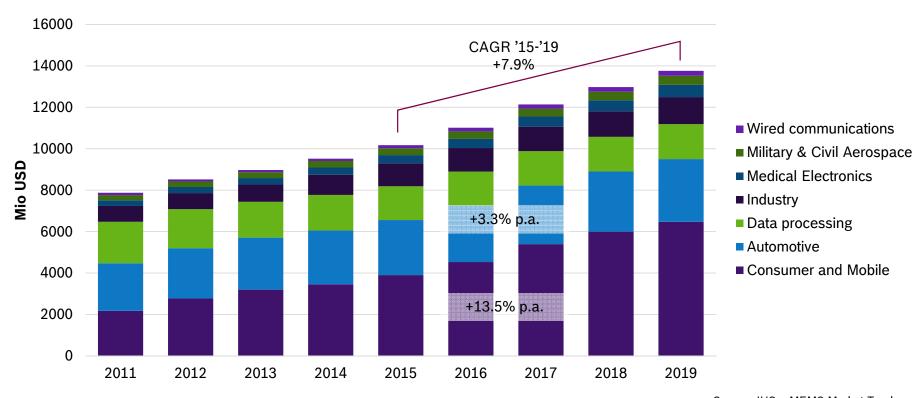
2010

2020



MEMS market overview

MEMS market by application



Source: IHS - MEMS Market Tracker - Q3 2015



MEMS @ Bosch Bosch – the MEMS pioneer

MEMS Pioneer

- ▶ Start of MEMS production in 1995
- **▶** Over 8 billion MEMS sensors produced
- ► More than 1,000 MEMS patents
- ▶ 100 % in-house from MEMS design to manufacturing

Value Proposition

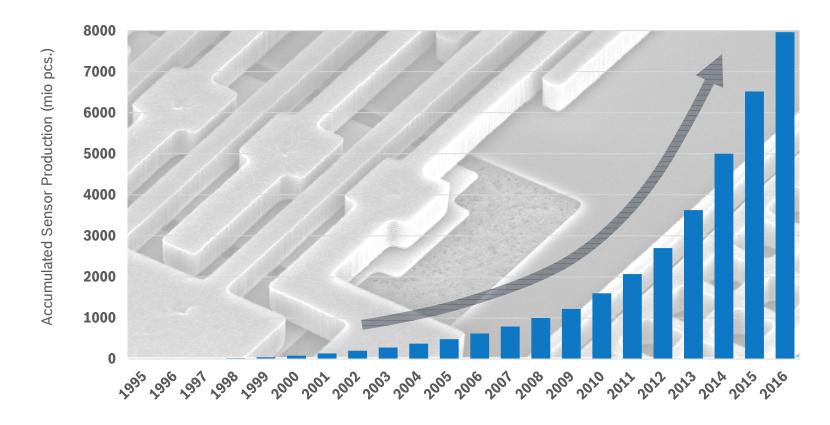
- ▶ Technology leadership for MEMS solutions: Driving technology roadmaps with in-house technologies
- ► Global support & systems capabilities: Support beyond component supply (in hardware & software)
- ▶ Supply capability & reliability: Capacity, volumes of scale, proven processes, industry's best reliability

Bosch is the #1 MEMS sensor supplier worldwide



MEMS @ Bosch

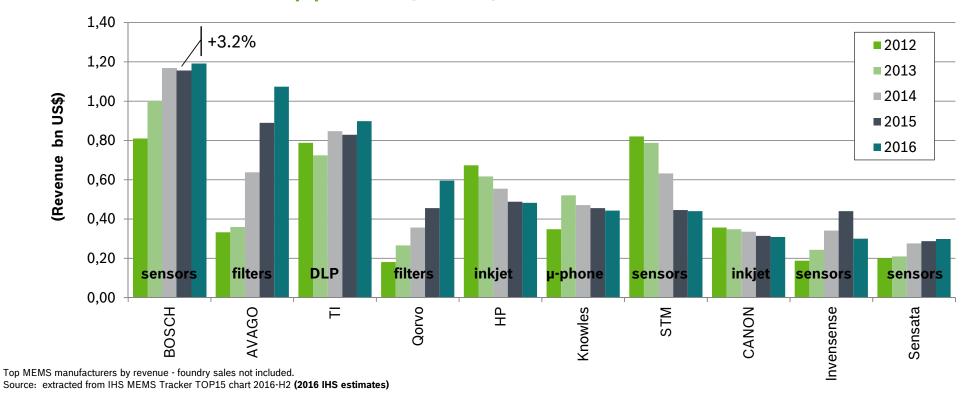
Volume MEMS production at Bosch (accumulated)





MEMS market overview

TOP 10 MEMS suppliers (2016)

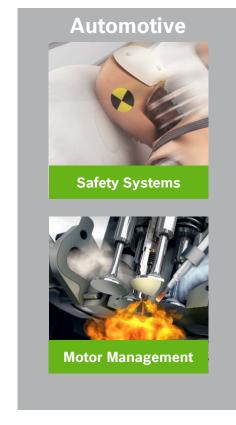


Bosch by far world's largest MEMS supplier



MEMS market overview

MEMS sensors – a multitude of markets







MEMS @ Bosch



Technology site in Reutlingen, Germany



MEMS @ Bosch

Wafer fab in Reutlingen

Employees

2 758

Production area

34 300 sqm

Minifactories

Wafer fab, sensor frontend, sensor backend, test center

Products

IC, power S/C (chip and packaged), sensors (packaged, customer specific mold package)



150 mm module

- 4 100 sqm
- 1 500 wafer starts/day
- Technologies:

BCD1, 2, 3, 3s, 4, 4s

CMOS, Bipolar, PSC bipolar, MOS

Pressure sensors

Inertial sensors

Process: ≥ 0.5 µm

200 mm module

- 4 600 sqm
- 1000 wafer starts/day
- Technologies:

BCD4, 4s, 6, 6sCu

Advanced CMOS, HVCMOS

Pressure sensors

Inertial sensors

Process ≥ 0.18 µm

02 AUTOMOTIVE MEMS

TECHNOLOGY & APPLICATIONS



Technology Requirements for automotive MEMS







- ► High functional requirements:
 - ▶ high accuracy, self test, advanced safety concepts
- ► High reliability / quality: 15 years, < 1 ppm
 - ▶ extreme environmental conditions (-40 .. +120°C)
- Additional 15 years of aftermarket supply
- ▶ Product life cycle up to 10 years, product development 3 years

High volume, reliability and quality are main success factors



Automotive sensors

More than 50 MEMS sensors in 1 car

Engine Management e.g. Diesel

1 Mass flow sensor

1 Pressure sensor [Barometric air pressure]

2 Pressure sensors [Manifold air pressure, oil]

1 High pressure sensor [Common Rail]

1 Pressure sensor [Tank pressure]

1 Pressure sensor [Start/stop function]

2 Acceleration sensors [Active engine mounting]

1 Pressure sensor [Diesel particulate filter]

Safety

2 High-g acceleration sensors [Airbag]

1 Angular rate sensor, 1 Low-g acceleration sensor [Roll-over sensing],

1 Acceleration sensor (Structure-borne sound sensor) [Airbag]

4 Acceleration sensors, 2 Pressure sensors [Peripheral airbag sensors]

2 Pressure sensors [Pedestrian safety]

1 Angular rate sensor, 1 Low-g acceleration sensor, 1 High pressure sensor [ESP (incl. ACC)]

1 Angular rate sensor [Active steering]

1 Acceleration sensor [eCall]

4 Pressure sensors, 4 acceleration sensors [TPMS]

1 Pressure sensor [Occupant detection]

Comfort

2 Pressure sensors [Automatic transmission]

5 Acceleration sensors [Active suspension]

1 Pressure sensor, 1 Humidity sensor,

2 Gas sensors [Air conditioning, air quality]

1 Angular rate sensor, 1 Acceleration sensor [Navigation]

3 Microphones [telephone]

1 Bolometer Array [Night vision]

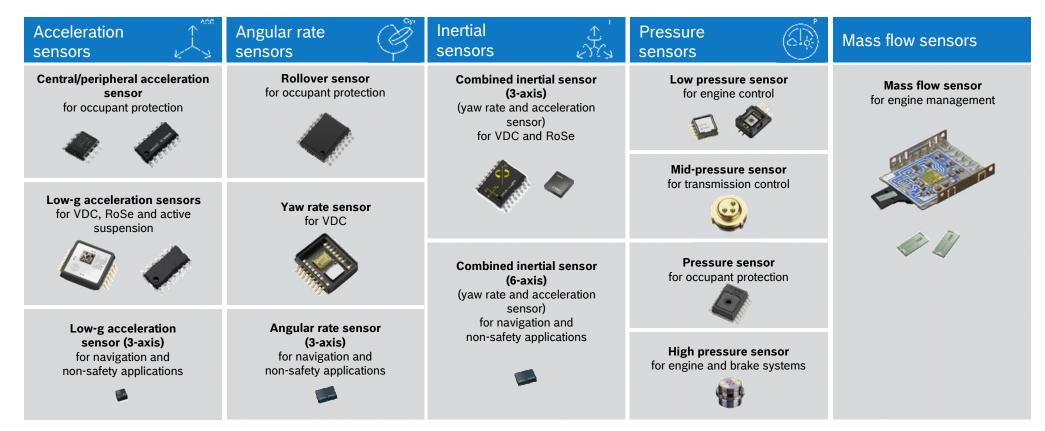
1 Acceleration sensor [Car alarm]

(Seldom: 16 Pressure sensors (up to 8 pressure sensors per seat)





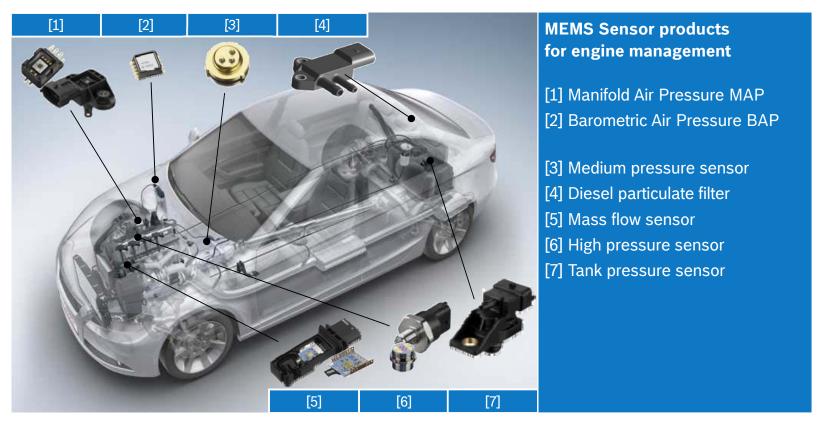
Automotive sensors Product portfolio





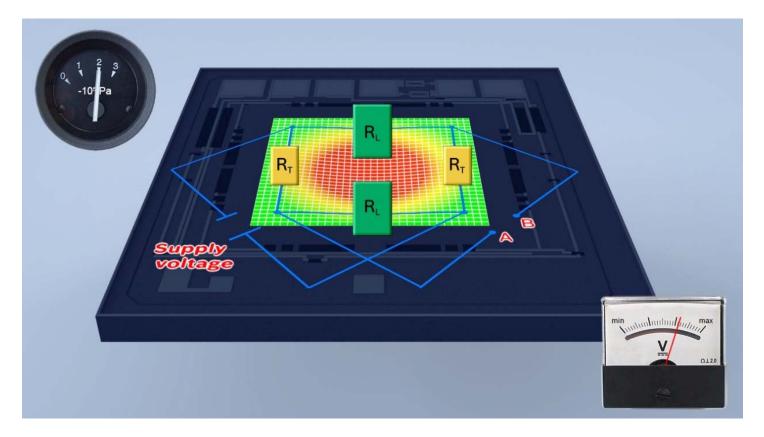
Automotive sensors

More MEMS sensors for engine management





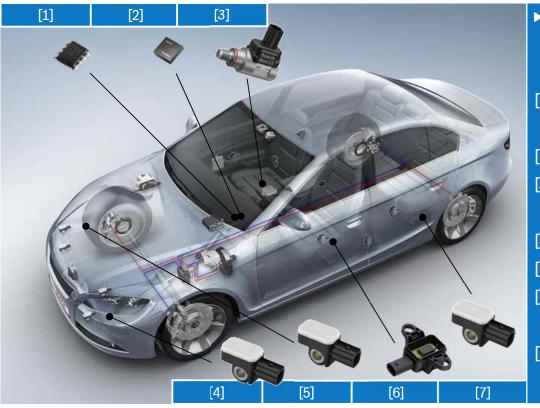
Automotive sensors – Pressure sensors Barometric pressure sensors: working principle





Header of section

MEMS sensors for safety systems

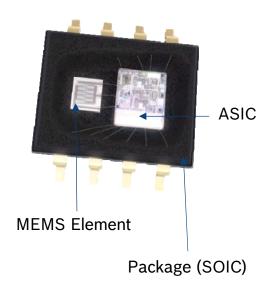


- ► MEMS sensors forsafety systems
- [1] Acceleration sensor (central)
- [2] Rollover sensor (central)
- [3] Occupant weight sensor iBolt
- [4] Pedestrian Contact Sensor PCS
- [5] Upfront Sensor UFS
- [6] Peripheral Pressure Sensor PPS (side)
- [7] Peripheral Acceleration Sensor PAS

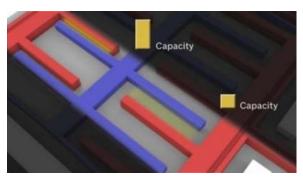


Automotive sensors – Acceleration sensors Working principle

Construction of an acceleration sensor



Functionality of an acceleration sensor

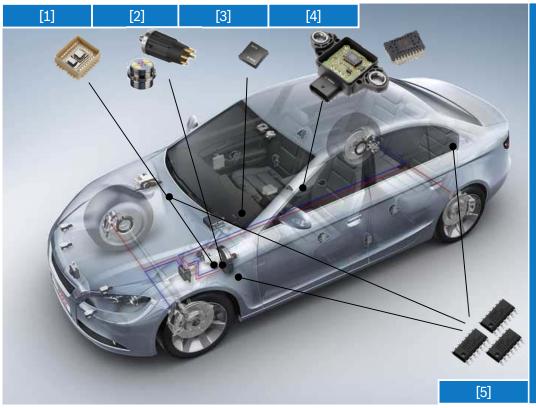


- Seismic mass moves due to external acceleration (crash, car movements, vibration, ...)
- Capacitance between MEMS fingers and seismic mass changes with acceleration



Automotive sensors

MEMS sensors for vehicle dynamics control VDC



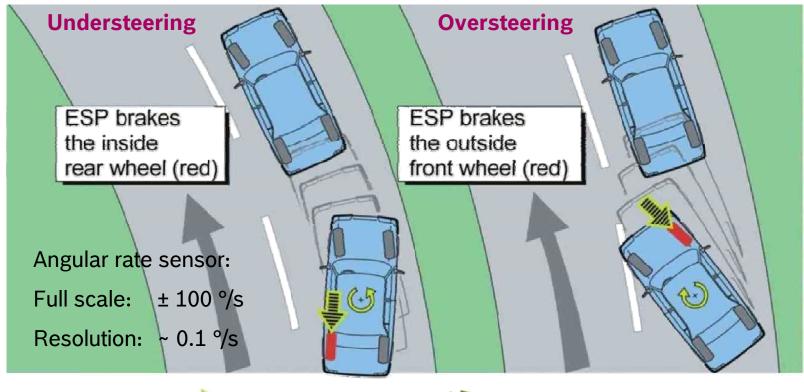
MEMS sensors for vehicle dynamics control VDC

- [1] Inertial sensor
- [2] High pressure sensor
- [3] Inertial sensor
- [4] Sensor cluster with yaw rate and acceleration sensor
- [5] Low-g acceleration sensor for active suspension



Automotive sensors – VDC applications

ESP® system – working principle









Automotive sensors – Angular rate sensors Measurement principle





Natural example

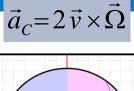
Coriolis effect (pseudo force)

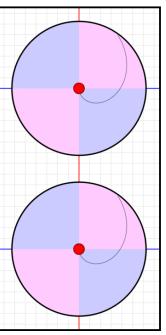
Idle observer

sees

- (i) a rotating plate and
- (ii) a straight downward moving sphere

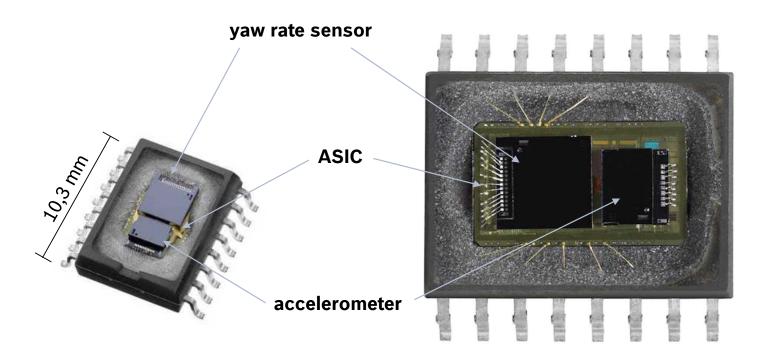
Observer on rotating plate sees a sphere moving on a curved trajectory: Coriolis effect





Automotive sensors – Combined inertial sensors SMI540

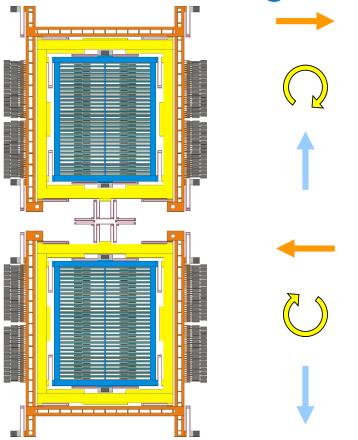
World's first ESP combi-inertial sensor (yaw rate and acceleration) in mold-package.

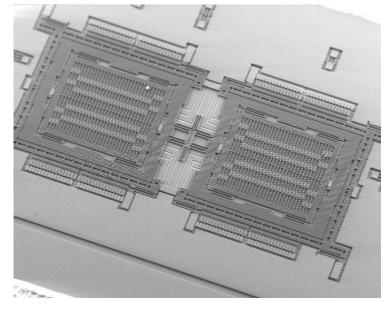




Automotive sensors – Angular rate sensors

Micromechanical sensing element





drive frame

drive



coriolis frame

detection frame

detection



Automotive sensors – Angular rate sensors

Noise and resolution limit - comparison

Device Sensitivity

► mechanical sensitivity Sm ~ 5.2 pm / (°/s)

► electrical sensitivity Se ~ 2.3 aF / (°/s)

Resolution Limit

~3 °/h (0.005 Hz)

▶ amplitude change in micromechanical structure

~4 fm

(compares to ~0.00001 x Si-Si distance or ~radius of atomic nucleus)

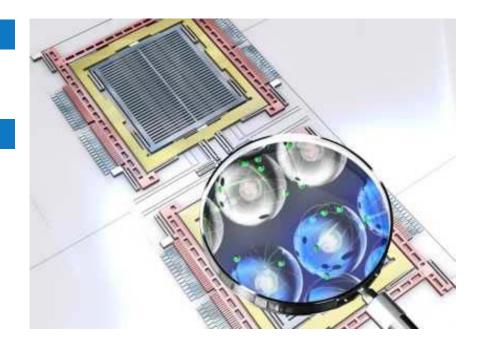
capacitance change

~2 zF

$$(\mu - n - p - f - a - z)$$

 10^{-6} 10^{-21}

(compares to charge variation of ~0.06 electrons (at 5V))





03 CE MEMS

DRIVING TECHNOLOGY INNOVATION



CE MEMS sensors in mobile devices





Inertial Measurement Unit Integrates accelerometer and gyroscope



Accelerometer
Detects acceleration
and orientation



eCompass
Combines accelerometer
and geomagnetic sensor



GyroscopeMeasures yaw rates



SoftwareIntelligently fuses raw
data from multiple sensors



MicrophoneHighly integrated MEMS-based microphone solution



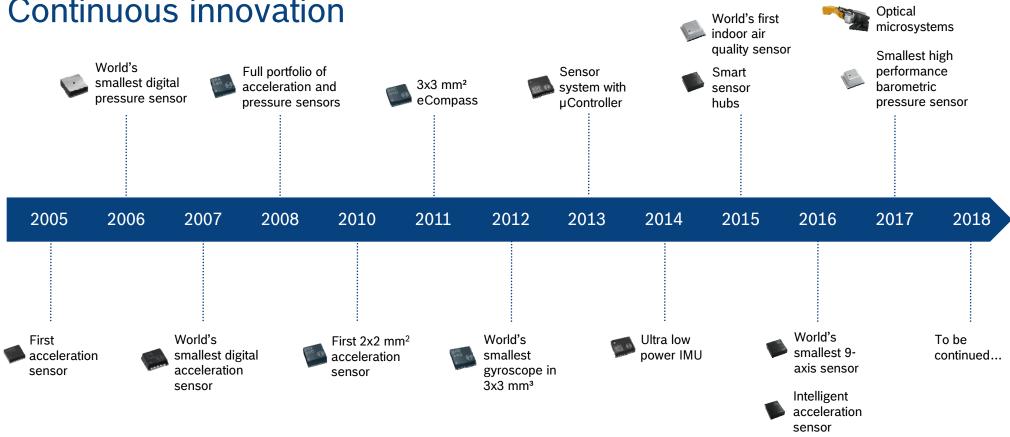
Environmental UnitMeasures pressure, humidity and temperature



Absolute Orientation Integrates accelerometer, gyroscope and magnetometer

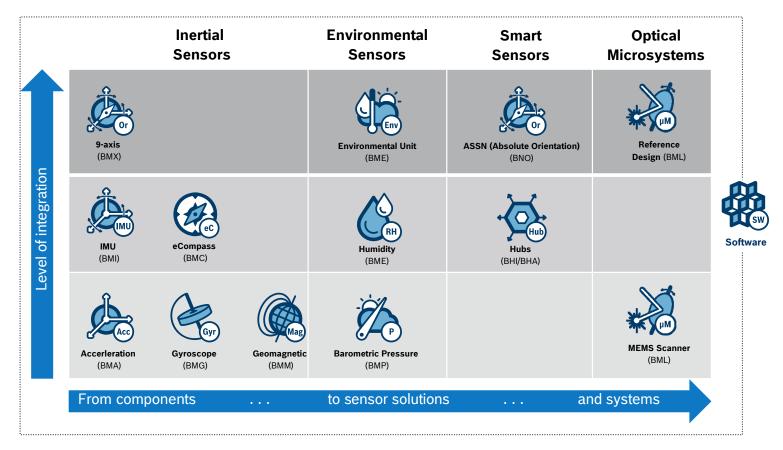


Consumer MEMS success story Continuous innovation





Bosch Sensortec is a full-portfolio provider





Today's state-of-the-art portfolio



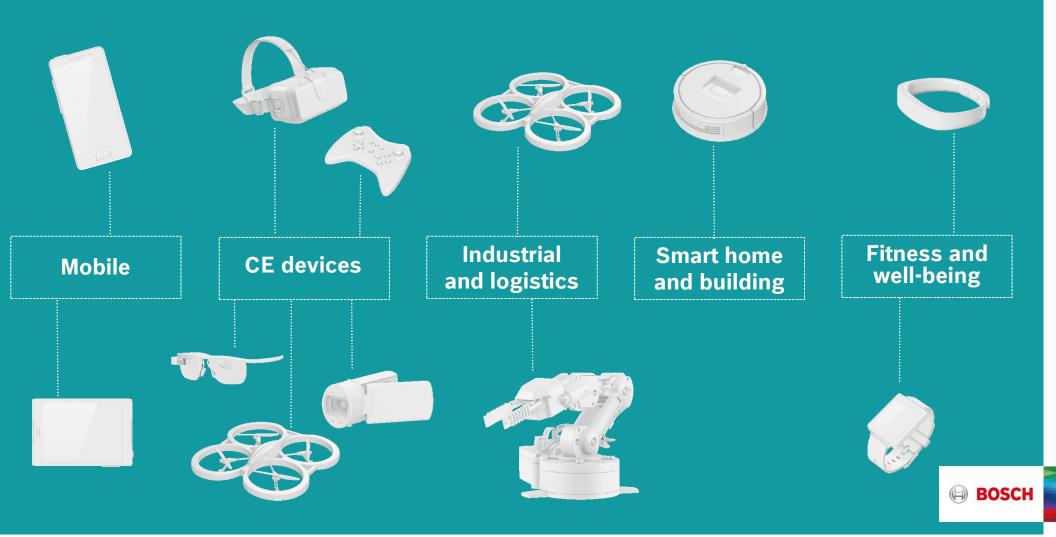








MEMS sensors – a multitude of devices



Technical challenges and solutions





Enabler for IoT - MEMS technology innovation

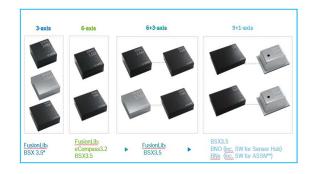
Technology is ready for IoT

Size / power

Continuing shrinking of sensor footprint / size and power consumption (e.g. accelerometer)

Integration / µC + software

Integration of multi-axis sensors + µC + SW in combo package (e.g. motion / orientation)



New measurants

Rise / emergence of novel sensor clusters

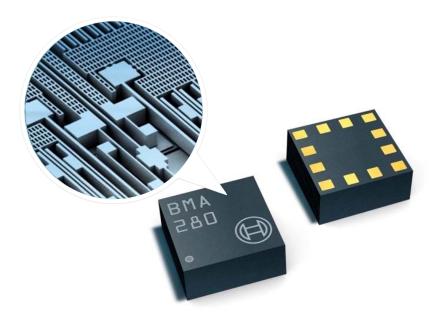
(e.g. environmental cluster → T, p, H, ...)





Old challenge

Shrinking the size / power consumption of components



Size / power

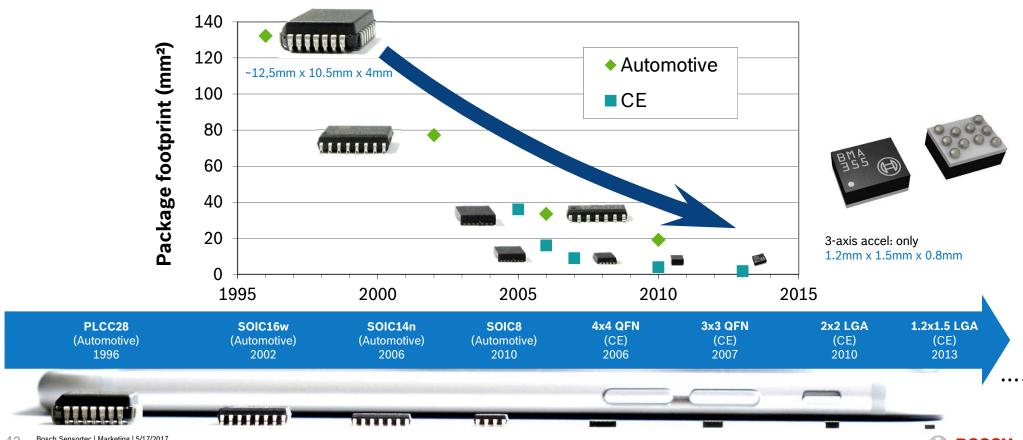
Continue shrinking of sensor footprint / size and power consumption (e.g. accelerometer)

Size alone is not an enabler anymore... but functional density increases



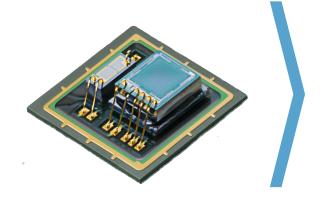
Old challenge

Continuous shrinking of sensor footprint / size of accelerometers



New challenge

Environmental sensing solutions



New drivers for new applications

- ► Pressure
- ► Temperature
- ► Humidity
- ▶ VOC (gas)

Size

► Sensor footprint <= 3 x 3 mm²

Power

► Low power << 1 mA (avg)

Accuracy

► High accuracy and fast setting time







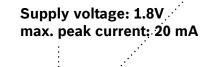


New challenge

BME680 environmental sensor

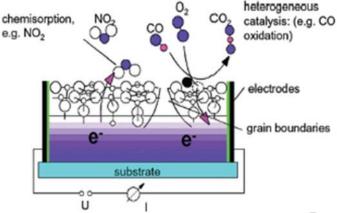
Dimension: 3.0 x 3.0 x 0.95 mm³ package with LGA metal lid

Minimized current consumption between 0.2mW to 2mW with maximum 20mW peak depending on working mode (low, medium or high power)

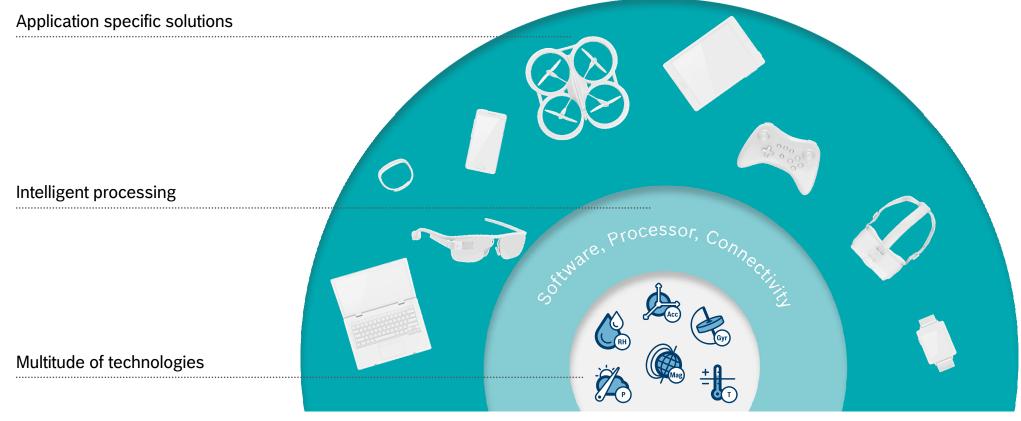


Integrated MEMS gas Technology

- ► Integration of gas sensor chip into BME module enables better gas sensor performance by compensation of P/T/H
- ► High sensitivity for VOC (10 ppb-1000 ppm)
- ► High stability of > 5 years with proven automotive-known reliability tests



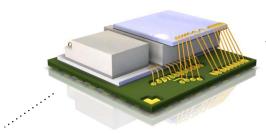
New challenge Total sensor solutions





New challenge

Data fusion at lowest power



Performance output ready to use

- Quaternion
- Linear acceleration
- Rotation
- ▶ Gravity
- ► Robust heading
- eCompass fast calibration
- ▶ Step counter
- ► Activity monitoring & interrupt
- ► Significant motion detection





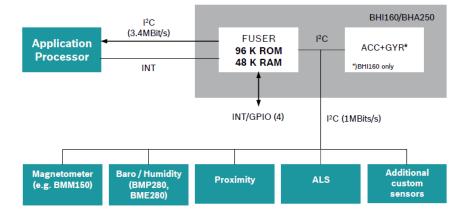






Smart Sensor Hub BHI160

- ▶ 3 x 3 x 0.95 mm³
- ➤ 32-bit floating-point microcontroller (optimized for sensor fusion)
- ▶ 96 kByte ROM, 48 kByte RAM
- ▶ 30 µA step detector / 1.59 mA full 9DoF Fusion @100Hz



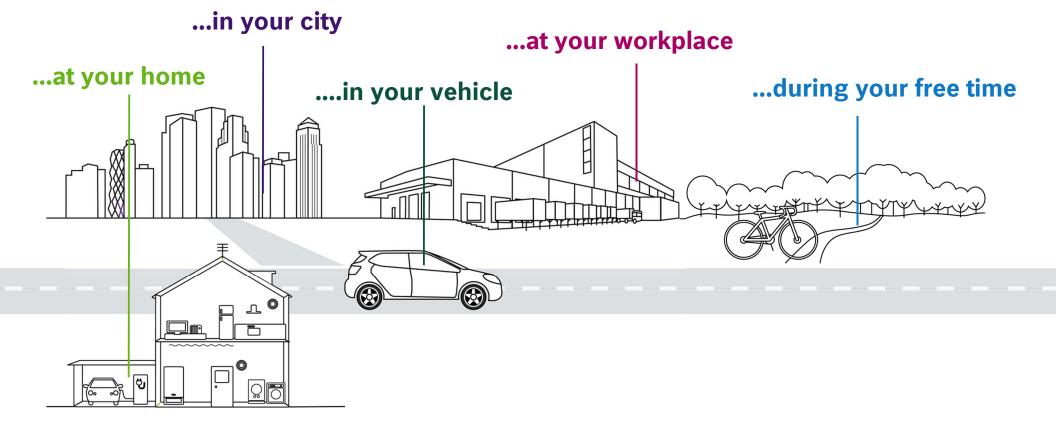


04 MEMS FOR IOT

CHALLENGES & SOLUTIONS

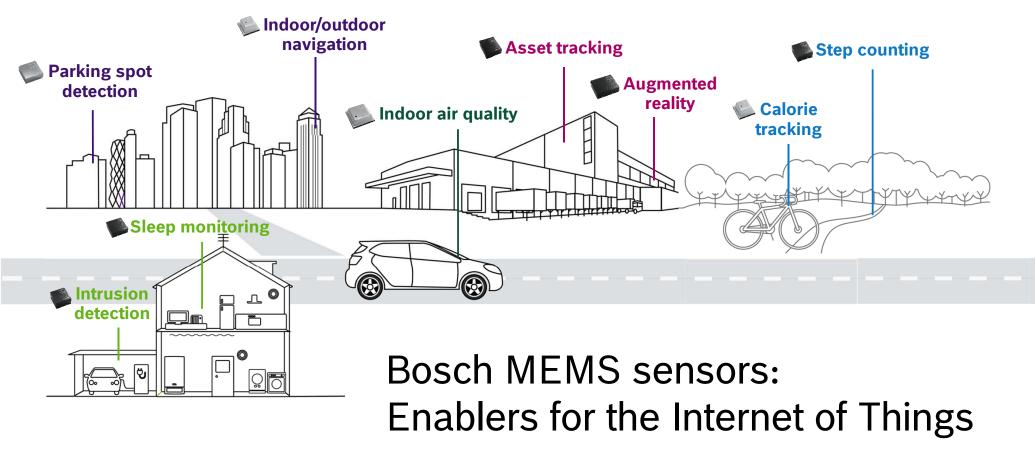


Bosch MEMS sensors – The hidden champions of your everyday life





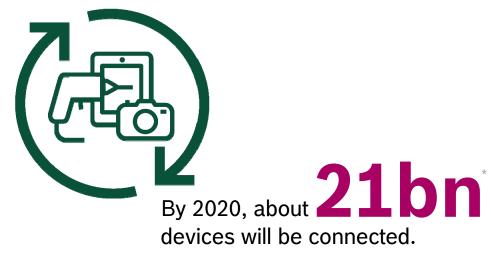
Bosch MEMS sensors – The hidden champions of your everyday life

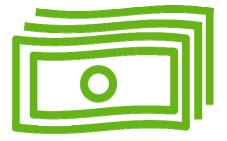




Role of smart sensors in the IoT Everything will be connected

Today, about **6bn*** devices are connected worldwide.





By 2020, the global market for loT solutions is expected to be worth some 250bn USD.

Source: *Gartner



IoT is about making life simpler and more exciting.

Everything should be "Simply. Connected" for the user.



But sensing everything in multiple and complex environments bears a lot of challenges...



Challenges and barriers

loT is...

... technologically demanding

CE sensor technology

- Many technologies available...
- ...but not always adapted for IoT
- Power (always-on applications), size, scalability, cost



Challenges and barriers

loT is...

...fragmented

System/application customization

- Different applications: home, vehicle, city, industry, entertainment
- Deep application know-how needed
- Small volume customers
- Lack of synergies & standardization



Challenges and barriers

Cooperation and collaboration

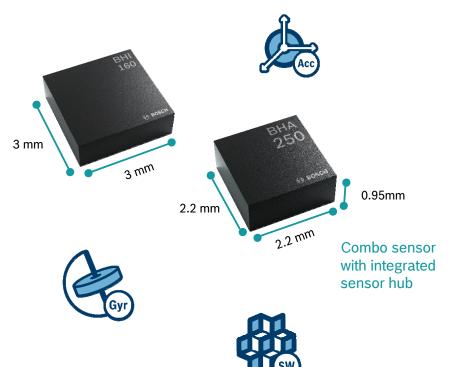
- Value is in end-to-end solution
- Large and diverse eco-system
- Business models not yet established
- Fast time to market (fast prototyping)

IoT is...

... complex



Smart sensor hubs



Integrated sensor hubs BHI160 and BHA250

SmartHub solutions combine Bosch Sensortec's...

- ► lowest power sensors (IMU < 1mA)
- best-in-class sensor data fusion software
- optimized microcontroller, "FUSER Core"
- ... to provide the lowest power solution without compromising features or performance.



Driving innovation and cooperation: Smart sensor hubs

Innovation:
Development of smart sensor
Solutions

Overcoming the challenge of TECHNOLOGY

- Leverage CORE MEMS- and system know-how
- Size, power, performance, embedded intelligence

Overcoming the challenge of FRAGMENTATION

- Platform solution with hardware and software
- APPLICATION know-how in the Bosch Group
- Application-specific software, e.g. AR/VR/PDR

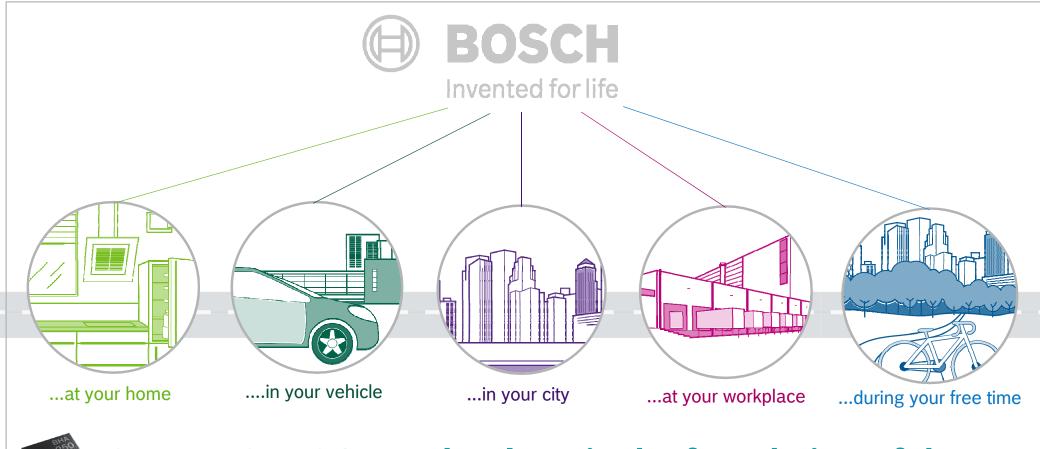
Overcoming the challenge of COMPLEXITY

- From components to systems and solutions
- Simple design and TURN-KEY solution
- COOPERATION with third parties, reference designs

Role of smart sensors

Smart sensors are sensing our world in multiple and complex environments, allow things to be "Simply.Connected" and act as the enablers of the IoT.







SMART SENSOR technology is the foundation of the IoT



Summary

- ▶ MEMS sensors are well established in automotive applications and mobile devices
- ► Additional requirements for the IoT:
 - ▶ Size
 - ► Power
 - ▶ New measurands: e.g. Environmental cluster
 - ▶ Connectivity
 - ▶ Intelligence
- ► IoT "Next Big Wave" for MEMS sensors.
- ► We believe that **intelligent & distributed** sensor and actuator solutions will be an important building block for all IoT implementations.
- ▶ Bosch is leading user and leading supplier (Dual Strategy) of MEMS sensors for IoT systems.
- ► We provide our unique cross industrial and vertical integration capabilities to enable our customers for IOT applications and services.



